

Bill of Materials

TI DESIGNS

TIDA-00399 SSD Power Delivery Interposer

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	Note
1	3	1p0V_AON, 1p0V_PG, EN_ASIC		Test Point, Miniature, Orange, TH	Keystone	5003	TH	
2	11	1p0V_ASIC, 1p8V_NAND, 3p3V_LOGIC, GND1, GND2, GND3, GND4, J_SNS_EXT, J_UVLO_EXT, VIN, VIN_DC_DC		Header, 100mil, 2x1, Gold, TH	Samtec	TSW-102-07-G-S	TH	
3	3	1p8V_AON, 1p8V_PG, EN_NAND		Test Point, Miniature, Blue, TH	Keystone	5117	TH	
4	3	3p3V_AON, 3p3V_PG, EN_LOGIC		Test Point, Miniature, White, TH	Keystone	5002	TH	
5	6	C1FB, C1J1, C1U1, C3J1, C3p3_2, CIN3	1 μ F	CAP, CERM, 1 μ F, 6.3 V, +/- 10%, X5R, 0603	Samsung	CL10B105KQ8NNNC	0603	
6	1	C1_LDO	10 μ F	CAP, CERM, 10 μ F, 25 V, +/- 10%, X5R, 0805	TDK	C2012X5R1E106K125 AB	0805	
7	5	C2FB, C2J1, C2U1, C3p3_3, C4J1	0.1 μ F	CAP, CERM, 0.1 μ F, 6.3 V, +/- 10%, X7R, 0603	MuRata	GRM188R70J104KA0 1D	0603	
8	2	C3p3_1, CIN2	10 μ F	CAP CER 10UF 6.3V 10% X5R 0603	TDK	C1608X5R0J106K080 AB	0603	
9	1	CIN1	100 μ F	CAP, CERM, 100 μ F, 6.3 V, +/- 20%, X6S, 1210	MuRata	GRM32EC80J107ME2 0L	1210	
10	2	D1, D2	3.3V	Diode, Zener, 3.3 V, 225 mW, SOT-23	ON Semiconductor	BZX84C3V3ET1G	SOT-23	
11	4	EN, VIN_DC_DC_S, VIN_PG, VIN_S		Test Point, Miniature, Red, TH	Keystone	5000	TH	

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12	6	H1, H2, H3, H4, H9, H11		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH		
13	6	H5, H6, H7, H8, H10, H12		Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C	N/A	
14	1	J1		Header (shrouded), 100mil, 15x2, Gold, TH	3M	D2530-6002-AR	TH	
15	1	J2		BANANA JACK, SOLDER LUG, RED, TH	Tenma	SPC15363	TH	
16	1	J3		BANANA JACK, SOLDER LUG, BLACK, TH	Tenma	SPC15354	TH	
17	1	J4		PCI Express M.2 connector, 0.5mm, B Key, Gold, R/A, SMD	JAE Electronics	SM3ZS067U310ABR1200		
18	1	JPWR		Header, 100mil, 3x1, Tin, TH	TE Connectivity	5-146278-3	TH	
19	3	Q1, Q2, Q3	25V	MOSFET, N-CH, 25 V, 0.68 A, SOT-23	Fairchild Semiconductor	FDV303N	SOT-23	
20	2	RD1, RD2	330Ω	RES, 330, 5%, 0.125 W, 0805	Susumu	RR1220P-331-D	0805	
21	1	REN_PD	3.0kΩ	RES, 3.0 k, 5%, 0.125 W, 0805	Panasonic	ERJ-6GEYJ302V	0805	
22	1	RHA_OUT	110kΩ	RES, 110 k, 0.1%, 0.125 W, 0805	Susumu	RG2012P-114-B-T5	0805	
23	1	RLA_GND	60.4kΩ	RES, 60.4 k, 0.1%, 0.125 W, 0805	Susumu	RG2012P-6042-B-T5	0805	
24	1	RSHUNT	0.01kΩ	RES, 0.01 ohm, 1%, 3W, TH	Bourns	PWR4412-2S-C-R0100-F	TH	
25	1	RWA_ADJ	0kΩ	RES, 0, 5%, 0.125 W, 0805	Vishay-Dale	CRCW08050000Z0EA	0805	
26	2	SCL, SDA		Test Point, Miniature, Yellow, TH	Keystone	5004	TH	
27	2	U1, UFB_LDO		256-TAPS DUAL CHANNEL DIGITAL POTENTIOMETER WITH NON-VOLATILE MEMORY, RUC0014A	Texas Instruments	TPL0102-100RUCR	RUC	

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	Note
28	1	U1_LDO		Single Output Fast Transient Response LDO, 1.5 A, Adjustable 1.21 to 20 V Output, 2.1 to 20 V Input, 6-pin SOT-223 (DCQ), -40 to 125 degC, Green (RoHS & no Sb/Br)	Texas Instruments	TPS7A4501DCQR	DCQ	

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